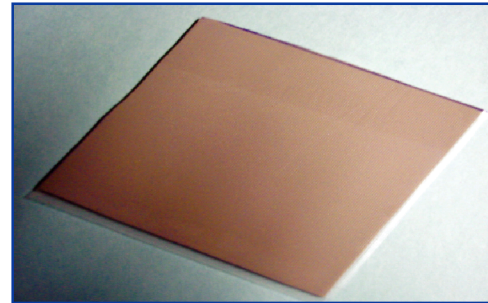


TIM-GAP NS

Cool it Right

DATA SHEET

Thermally Conductive Non Silicone Insulating Gap Filler



Descriptions

TIM-GAP NS is Non Silicone Gap Pad designed to meet industry's rapidly growing need to replace silicone gap fillers due to the silicone oil extraction and contamination. **TIM-GAP NS** are specially formulated with acrylic polymer and conductive fillers, available with and without polyester mesh reinforcement.

Key Features

- High Thermal Conductivity
- Electrically Insulating
- Smooth and highly compliant surface
- Eliminates Silicone bleed & contamination
- Clean and easy to apply

Applications

- Interface for discrete semiconductors requiring low pressure or spring clamp mounting
- Optical Applications
- Medical devices
- Hard Drives
- Consumer electronics
- Industrial controls

| PHYSICAL PROPERTY | TEST METHOD | TIM-GAP NS |
|---|----------------------|------------------|
| Type | | Non-Silicone |
| Color | Visual | Dark Gray |
| Operating Temp. range °C | | -40 to 105 |
| Tensile Strength. MPa | ASTM D-412 | 2.0 |
| Hardness. Shore 00 | ASTM D-2240 | 53 |
| Thermal Conductivity. W/m ² k | ASTM D-5470 Modified | 1.6 |
| Thermal Resistance. °C-inch ² /W 0.020" thickness | ASTM D-5470 Modified | 0.72 |
| Breakdown Voltage KV/mm | ASTM D-149 | 11 |
| Volume Resistivity, Ohm-cm | ASTM D257 | 10 ¹⁵ |
| Available thickness, inch. | | 0.02, 0.04, 0.08 |

Availability

- **TIM-GAP NS** is available in die-cut or sheet. Available with and without polyester mesh reinforcement.
- The material is compatible with dispensing equipment for high volume production.
- Materials are available standard and/or special shape and size.
- Tooling charges vary depending on tolerances and complexity of the part



Disclaimer: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performances. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not be construed as recommendations to infringe any patent